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- 13 metal and adhesion and intergranular near11 etch\$4 and plat\$4 and immers\$4 USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; IBM TDB USPAT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;			· · · · · · · · · · · · · · · · · · ·		
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near11 etch\$4 and plat\$4 and immers\$4  US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; Immers\$4 and adhesion US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;					0000/00/05 11 1=
EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT;	-	13			2002/03/07 11:17
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT; DERWENT;			near11 etch\$4 and plat\$4 and immers\$4		
- 28 intergranular and etch\$4 and plat\$4 and USPAT; US-PGPUB; EPO; JPO; DERWENT;					
- 28 intergranular and etch\$4 and plat\$4 and USPAT; 2002/03/07 11:31 immers\$4 and adhesion USPAT; US-PGPUB; EPO; JPO; DERWENT;					
immers\$4 and adhesion  US-PGPUB; EPO; JPO; DERWENT;	[_	28	intergranular and etch\$4 and plat\$4 and		2002/03/07 11:31
EPO; JPO; DERWENT;		20			
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				DERWENT;	
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-	0	intergranular and 216.34.ccls	USPAT;	2002/03/07 11:32
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_ •	0	216.34.ccls	USPAT;	2002/03/07 11:32
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT; IBM TDB	
	1	216/34.ccls. and intergranular	USPAT;	2002/03/07 11:32
-	_	210/34.ccis. and intergrandial	US-PGPUB;	2002,03,0, 11.32
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
- ,	143	216/34.ccls.	USPAT;	2002/03/07 11:34
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	14	216/34.ccls. and metal and plate and	USPAT;	2002/03/07 11:37
		adhesion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	600	Hadbasian muomatian Hand mata	IBM TDB	2002/03/07 11:38
_	628	"adhesion promotion" and metal	USPAT; US-PGPUB;	2002/03/07 11:38
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"adhesion promotion" and metal and	USPAT;	2002/03/07 11:38
		intergranualr	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	2	intergranualr	USPAT;	2002/03/07 11:39
	_	incergrandari	US-PGPUB;	2002,03,0, 11103
}			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000/00/07 44 00
_	4381	intergranular	USPAT;	2002/03/07 11:39
		,	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	intergranular and "adhesion promotion" and	USPAT;	2002/03/07 11:39
		metal and etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	0	intergranular and adhesion and promotion	IBM TDB USPAT;	2002/03/07 11:40
		and metal and etch	US-PGPUB;	2002,00,011.40
	1		EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3846		USPAT;	2002/03/07 11:53
		meta\$12 and etc\$12	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	205	inter\$12 and adhes\$12 and promot\$12 and	USPAT;	2002/03/07 11:56
		meta\$12 and etched	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1210017	car andnot vehicle	IBM TDB USPAT;	2002/03/07 11:59
-	1318017	car andnot venicie	US-PGPUB;	2002/03/07 11:39
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

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-	467135	intergranular andnot copper	USPAT;	2002/03/07 12:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2260		IBM TDB	2002/03/07 12:00
_	3369	intergranular not copper	USPAT;	2002/03/07 12:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1011		IBM TDB USPAT;	2002/03/07 12:00
-	1011	intergranular and copper	US-PGPUB;	2002/03/07 12.00
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	intergranular and adhesion near3 promotion	USPAT;	2002/03/07 12:09
_	U	Intergranular and admession hears promotion	US-PGPUB;	2002/03/07 12:03
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	1030	intergranular near3 etch or adhesion near3	USPAT;	2002/03/07 12:10
	1030	promotion	US-PGPUB;	2002,03,0. 12.10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	intergranular near3 etch and promotion	USPAT;	2002/03/07 12:10
		Intergrandial nears even and promotion	US-PGPUB;	2002,00,07 12.10
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	0	intergranular near3 etch and adhere	USPAT;	2002/03/07 12:11
	_	intergrandral nears even and dance	US-PGPUB;	2002,00,0. 12:11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	6	intergranular and etch and adhere	USPAT;	2002/03/07 13:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	118	"copper strike" and nickel and (iron	USPAT;	2002/03/07 13:16
		ferrous ferric)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	89	intergranular and etch\$4 and plat\$4 and	USPAT;	2002/03/07 13:19
		immers\$4	US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
			IBM TDB	
-	7	······	USPAT;	2002/03/07 14:15
		immers\$4 and polymer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	,	USPAT;	2002/03/07 14:18
		and plate and etch and (copper nickel) and	US-PGPUB;	
		(immersion immerse) and polymer	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	53		USPAT;	2002/03/07 15:54
		and plate and etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"3265526". PN.	USPAT	2002/03/07 14:27
-	1	"3573100". PN.	USPAT	2002/03/07 14:31
-	1	"3632498". PN.	USPAT	2002/03/07 14:31
-	1	"3650861".PN.	USPAT	2002/03/07 14:34
-	1	"3706600".PN.	USPAT	2002/03/07 15:37
I <b>-</b>	1	"3711385".PN.	USPAT	2002/03/07 15:37

-	1	"3778307".PN.	USPAT	2002/03/07 15:38
-	1	"3864163".PN.	USPAT	2002/03/07 15:39
-	] 1	"3878083".PN.	USPAT	2002/03/07 15:39
-	1	"3864163".PN.	USPAT	2002/03/07 15:40
-	1	"3878083".PN.	USPAT	2002/03/07 15:40
_	1	"3882002".PN.	USPAT	2002/03/07 15:40
1_	i i	"3948736".PN.	USPAT	2002/03/07 15:41
_	1	"3950240".PN.	USPAT	2002/03/07 15:41
-	l		1	
-	1	"4005003".PN.	USPAT	2002/03/07 15:43
-	1	"4039400".PN.	USPAT	2002/03/07 15:44
-	1	"4068025".PN.	USPAT	2002/03/07 15:46
-	1	"4039400".PN.	USPAT	2002/03/07 15:50
-	1	"4068025".PN.	USPAT	2002/03/07 15:50
-	1	"4140813".PN.	USPAT	2002/03/07 15:51
-	1	"4140813".PN.	USPAT	2002/03/07 15:52
<del>-</del>	1	"4255247".PN.	USPAT	2002/03/07 15:53
_	1	"4272354".PN.	USPAT	2002/03/07 15:53
_	1	"4328080".PN.	USPAT	2002/03/07 15:53
_	1	"4331528".PN.	USPAT	2002/03/07 15:53
_		"4331528".PN.	USPAT	2002/03/07 15:54
	1			1
-	35	1 ,	USPAT;	2002/03/12 11:48
		and plate and etch and substrate	US-PGPUB;	
			EPO; JPO;	
1	1		DERWENT;	
	1		IBM TDB	
_	3	("5205473").PN.	USPAT;	2002/03/08 11:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	]		1	
		HEOODAOE H. DVI	IBM TDB	0000/00/00 00 00
_	1	"5092485".PN.	USPAT	2002/03/08 08:39
-	48	5205473.uref.	USPAT;	2002/03/08 08:38
			US-PGPUB;	
			EPO; JPO;	
	i		DERWENT;	
			IBM TDB	
_	50	"5205473"	USPAT	2002/03/08 08:39
_	48	5205473.uref.	USPAT	2002/03/08 08:39
_	0	"99/40764"	USPAT;	2002/03/08 12:27
		337 40 704	US-PGPUB;	2002/03/00 12.2/
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	8	sadey	USPAT;	2002/03/08 12:35
		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	11	"5869130"	USPAT;	2002/03/08 12:52
			US-PGPUB;	-,
			EPO; JPO;	
			DERWENT;	
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	54500	nah intangganulas	IBM TDB	1 2002 /02 /02 12 52
-	54522	pcb intergranular	USPAT;	2002/03/08 12:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	10	pcb and intergranular	USPAT;	2002/03/08 12:56
		<u> </u>	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
1_	3.00	(adhere adhesion) and inter	IBM TDB	2002/02/00 10:55
-	368	(adhere adhesion) and intergranular	USPAT;	2002/03/08 12:56
			US-PGPUB;	1
			EPO; JPO;	1
1			DERWENT;	]
			IBM TDB	
			·	·

_	18	(adhere adhesion) and intergranular and	USPAT;	2002/03/08 13:04
		etch and (organic polymer)	US-PGPUB;	
		Coon and (games position)	EPO; JPO;	
ĺ			DERWENT;	
			IBM TDB	
	500244	(adhere adhesion) mear promotion	USPAT;	2002/03/08 13:05
-	300244		· ·	2002/03/08 13.03
		(intergranular "grain boundary") and etch	US-PGPUB;	
		and (organic polymer)	EPO; JPO;	
			DERWENT;	
			IBM TDB	2222/22/22 12 25
-	1173	(adhere adhesion) near promotion	USPAT;	2002/03/08 13:05
		(intergranular "grain boundary") and etch	US-PGPUB;	
		and (organic polymer)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1173	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:05
		(intergranular "grain boundary") and etch	US-PGPUB;	
		and (organic polymer)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	933	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
_	955	(intergranular "grain boundary") near1	US-PGPUB;	2002/03/00 13:00
		etch and (organic polymer)	EPO; JPO;	
		etch and (organic polymer)		
			DERWENT;	
			IBM TDB	000040040040
-	923	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
		(intergranular "grain boundary") near1	US-PGPUB;	
		etch and (organic polymer)and circuit	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	923	(adhere adhesion) near1 promotion	USPAT;	2002/03/08 13:06
		(intergranular "grain boundary") near1	US-PGPUB;	
		etch and (organic polymer) and circuit	EPO; JPO;	
		1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	DERWENT;	
			IBM TDB	
_	0	(adhere adhesion) near1 promotion near1	USPAT;	2002/03/08 13:07
		(intergranular "grain boundary") nearl	US-PGPUB;	2002/03/00 13:07
		etch and (organic polymer) and "circuit	EPO; JPO;	
		board"	DERWENT;	
		Doard	1	
		(- N Ni )1	IBM TDB	2002/02/00 12:07
-	0	(adhere adhesion) near1 promotion and	USPAT;	2002/03/08 13:07
		(intergranular "grain boundary") nearl	US-PGPUB;	
		etch and (organic polymer) and "circuit	EPO; JPO;	
		board"	DERWENT;	
			IBM TDB	
-	2	(adhere adhesion) nearl promotion and	USPAT;	2002/03/08 13:11
		(intergranular "grain boundary")	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"(adhere adhesion) nearl promotion".ti.	USPAT;	2002/03/12 11:00
		•	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
1 -	58	"adhesion promotion".ti.	USPAT;	2002/03/08 15:11
		and an in the interest of the	US-PGPUB;	=====================================
			EPO; JPO;	
			DERWENT;	
	1	#2500003# DM	IBM TDB	2002/02/09 14-20
	1	"3508983".PN.	USPAT	2002/03/08 14:38
-	1	"3698940".PN.	USPAT	2002/03/08 14:38
-	1	"3698940".PN.	USPAT	2002/03/08 14:38
-	1	"3873499".PN.	USPAT	2002/03/08 14:38
-	1	"3978252".PN.	USPAT	2002/03/08 14:38
-	1	"4042729".PN.	USPAT	2002/03/08 14:38
-	1	"4100312".PN.	USPAT	2002/03/08 14:38
-	1	"4159222".PN.	USPAT	2002/03/08 14:38
-	1	"4499152".PN.	USPAT	2002/03/08 14:38
- '	1	"4574031".PN.	USPAT	2002/03/08 14:38
-	1	"4897118".PN.	USPAT	2002/03/08 14:38
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	1	"4902556".PN.	USPAT	2002/03/08 14:38
-	1	"4976990".PN.	USPAT	2002/03/08 14:38
-	1	"5061550".PN.	USPAT	2002/03/08 14:38
-	1	"5071701".PN.	USPAT	2002/03/08 14:38
-	1	"5073456".PN.	USPAT	2002/03/08 14:38
-	1	"5153024".PN.	USPAT	2002/03/08 14:38 2002/03/08 15:12
-	8	"intergranular etch" and adhesion	USPAT;	2002/03/08 15:12
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	"boundary layer" nearl1 etch and adhesion	USPAT;	2002/03/08 15:33
	_	boundary rayer heariff even and danceron	US-PGPUB;	2002,03,00 10.33
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	"4353954".PN.	USPAT	2002/03/08 15:14
-	112	metal near polymer near adhesion	USPAT;	2002/03/08 16:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1126	427/304.ccls.	USPAT;	2002/03/08 16:13
			US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
_	175	427/304.ccls. and adhesion and polymer	IBM TDB USPAT;	2002/03/08 16:13
-	175	427/304.ccis. and adhesion and polymer	US-PGPUB;	2002/03/08 10:13
	}		EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3466	bisphenol and plastic near11 can and coat\$	USPAT;	2002/03/12 09:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	334	bisphenol and plastic near11 can and coat\$	USPAT;	2002/03/12 09:24
		and food	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1.00		IBM TDB	0000/00/10 10 10
_	198		USPAT;	2002/03/12 10:12
		"reinforcing bar" and coat\$ and bridge	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	1	"5372449".PN.	USPAT	2002/03/12 09:37
_	1	"5175032".PN.	USPAT	2002/03/12 09:37
-	1	(bisphenol or plastic or polymer) and	USPAT;	2002/03/12 10:15
		"reinforcing bar" and coat\$ and bridge and	US-PGPUB;	
		etch	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	9	intergranular near3 etch and adhesion	USPAT;	2002/03/12 10:41
	]		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	intermenular nearly otah and adhesis TVD	IBM TDB	2002/02/12 10:42
-	0	intergranular near3 etch and adhesion AND	USPAT;	2002/03/12 10:43
		PROMOT\$4	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	926	(adhere adhesion) nearl promotion	USPAT;	2002/03/12 11:00
	720	, amount promotion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
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-	3	(adhere adhesion) nearl promotion and	USPAT;	2002/03/12 11:06
		"copper strike" and etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	(	IBM TDB	2002/03/12 11:41
_	5	(adhere adhesion) near1 promotion and	USPAT; US-PGPUB;	2002/03/12 11:41
		"copper strike"	EPO; JPO;	
	}		DERWENT;	
1	1		IBM TDB	
_	0	"09/628036"	USPAT;	2002/03/12 11:41
		037 020030	US-PGPUB;	2002, 00, 22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	14	"628036"	USPAT;	2002/03/12 11:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("6036758").PN.	USPAT;	2002/03/12 12:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	(III - 00 / 107 CAII)	IBM TDB	2002/02/12 12 11
-	0	("wo 99/40764").CCLS.	USPAT;	2002/03/12 12:14
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	0	"wo 99/40764"	USPAT;	2002/03/12 12:14
		WO 99740704	US-PGPUB;	2002/03/12 12:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"99/40764"	USPAT;	2002/03/12 12:14
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
<b>-</b>	17	"40764"	USPAT;	2002/03/12 12:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_	"40764" and adhesive	IBM TDB USPAT;	2002/03/12 12:15
-	0	40704 and adnesive	US-PGPUB;	2002/03/12 12:13
	]		EPO; JPO;	
	[		DERWENT;	
			IBM TDB	
_	0	("wo9940764").PN.	USPAT;	2002/03/12 12:23
]		,	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	("9940764").PN.	USPAT;	2002/03/12 12:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	[	0000.0754	IBM TDB	0000/00/10 10 1
-	0	wo009940764	USPAT;	2002/03/12 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	wo9940764	USPAT;	2002/03/12 15:00
-	0	WUJJ4U/04	US-PGPUB;	2002/03/12 13:00
		·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
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-	0	wo009617975	USPAT;	2002/03/12 15:00
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		0.017075	IBM TDB	2002/02/12 15:01
-	0	wo9617975	USPAT;	2002/03/12 15:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0	U 0.61 7.07 F.U	IBM TDB	2002/03/12 15:01
-	1	"wo9617975"	USPAT; US-PGPUB;	2002/03/12 13.01
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	5	"9617975"	USPAT;	2002/03/12 16:26
_	,	9017373	US-PGPUB;	2002/03/12 10:20
			EPO; JPO;	
	,		DERWENT;	
			IBM TDB	
	8	"9619097"	USPAT;	2002/03/13 12:52
		3013037	US-PGPUB;	2002/03/13 12:32
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	("copper strike" and adhesion).ti.	USPAT;	2002/03/13 13:02
		Copper berrie and dancoron, er.	US-PGPUB;	2502,00,10 10.02
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	423	("intergranular" or "grain boundary" and	USPAT;	2002/03/13 13:07
	723	adhesion).ti.	US-PGPUB;	2002/03/13 13:07
		addlesion, .c.i.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	(("intergranular etch" or "grain	USPAT;	2002/03/13 13:10
	_	boundary") and adhesion).ti.	US-PGPUB;	2002/03/13 13:10
		boundary , and dancoron, er.	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	JP03130142A	USPAT;	2002/03/13 13:12
	-	020013011111	US-PGPUB;	1
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
-	2	("grain boundary" or intergranular) and	USPAT;	2002/03/13 13:15
		adhesion near5 promotion	US-PGPUB;	
		•	EPO; JPO;	
	!		DERWENT;	
			IBM TDB	
-	1231	("grain boundary" or intergranular) and	USPAT;	2002/03/13 13:16
	1	adhesion	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	13	("grain boundary" or intergranular) near5	USPAT;	2002/03/13 14:34
		etch and adhesion	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	"4797182".PN.	USPAT	2002/03/13 13:22
-	19		USPAT;	2002/03/13 15:27
		surface roughening) near5 etch near5	US-PGPUB;	
		plating and adhesion near5 (enhanced	EPO; JPO;	
		enhance enhances enhancing improve	DERWENT;	
	1	improves improving improved)	IBM TDB	
	1	"6010768".PN.	USPAT	2002/03/13 15:08

	0150	T 400 (0001-	tionam.	2002/02/12 15:00
_	2150	428/209.ccls.	USPAT; US-PGPUB;	2002/03/13 15:29
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	337	428/209.ccls. and (etch etched roughen	USPAT;	2002/03/13 15:31
		"grain boundary" intergranular) and (adhere adhesion)	US-PGPUB;	
		(adhere adhesion)	EPO; JPO; DERWENT;	
			IBM TDB	
_	1035949	428/209.ccls. and (etch etched roughen	USPAT;	2002/03/13 15:33
		"grain boundary" intergranular) and	US-PGPUB;	
		(adhere adhesion) (copper nickel tin	EPO; JPO;	
		silver bismuth gold cadmium)	DERWENT; IBM TDB	
_	310	428/209.ccls. and (etch etched roughen	USPAT;	2002/03/13 15:33
	310	"grain boundary" intergranular) and	US-PGPUB;	2002,00,10 10.00
		(adhere adhesion) and (copper nickel tin	EPO; JPO;	
		silver bismuth gold cadmium)	DERWENT;	
		,	IBM TDB	
-	251	428/209.ccls. and (etch etched roughen	USPAT;	2002/03/16 10:50
		"grain boundary" intergranular) and (adhere adhesion) and (copper nickel tin	US-PGPUB; EPO; JPO;	
		silver bismuth gold cadmium) and metal and	DERWENT;	
		substrate	IBM TDB	
-	3	("5800859").PN.	USPAT;	2002/03/16 11:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	3	("3,650,861").PN.	USPAT;	2002/03/16 12:13
		( 0,000,000 , 0000	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	5	("3,773,577").PN.	IBM TDB USPAT;	2002/03/16 13:19
		( 5, 775, 577 ) . EW.	US-PGPUB;	2002/03/10 13.19
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("6162503").PN.	USPAT; US-PGPUB;	2002/03/16 13:22
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("5,869,130").PN.	USPAT;	2002/03/16 15:51
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1	surfeel	USPAT;	2002/03/16 16:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	34	etch and plate and (electroless	IBM TDB USPAT;	2002/03/16 16:11
	34	electroplate "immersion plate") and	US-PGPUB;	1002,00,10 10.11
		"hydrogen peroxide" and (sulfonic SO3H)	EPO; JPO;	
			DERWENT;	
		otah and plate and /alastuslass	IBM TDB	2002/02/10 00 50
-	1	etch and plate and (electroless electroplate "immersion plate") and	USPAT; US-PGPUB;	2002/03/18 09:59
	-	"hydrogen peroxide" near10 (sulfonic SO3H)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	689	thiazole and "hydrogen peroxide" near10	USPAT;	2002/03/18 10:01
		acid	US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
L	L			

-	3		USPAT;	2002/03/18 10:02
		acid and "printed circuit board"	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3366	"aspect ratio" near3 "5"	USPAT;	2002/03/19 09:06
	i		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	117	"aspect ratio" near3 "5" and etch	USPAT;	2002/03/19 09:07
			US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
-	3	"aspect ratio" near3 "5" and etch and	USPAT;	2002/03/19 09:10
		grain and boundary	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	/ /
-	0	"aspect ratio\$2" near3 "5" and etch and	USPAT;	2002/03/19 09:11
		(grain or boundary)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	33	aspect near2 ratio\$2 near3 "5" and etch	USPAT;	2002/03/19 09:15
		and (grain or boundary)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	aspect near2 ratio\$2 near3 etch near22	USPAT;	2002/03/19 09:15
		(grain or boundary)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	53	1 1 2 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2002/03/19 11:29
		or boundary)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	"40764" and phenyl	USPAT;	2002/03/19 11:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		48 00407648) 703	IBM TDB	0000/00/10/11 21
-	0	("wo9940764").PN.	USPAT;	2002/03/19 11:31
			US-PGPUB;	
			EPO; JPO;	
	a contain		DERWENT;	
	3	("0040764") PN	IBM TDB	2002/03/19 11:34
-	3	("9940764").PN.	USPAT;	2002/03/19 11:34
			US-PGPUB; EPO; JPO;	
1			DERWENT;	
		CDIECED in and HAME in	IBM TDB	2002/03/19 11:35
_	2	GRIESER.in. and HAUF.in.	USPAT;	2002/03/19 11:33
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	T. Maria		IBM TDB	
1_	3	CDIESED in and copper	USPAT;	2002/03/19 11:35
-	3	GRIESER.in. and copper	US-PGPUB;	2002/03/19 11:33
			EPO; JPO;	
			DERWENT;	
	t .		IBM TDB	
_	209	GRIESER.in.	USPAT;	2002/03/19 12:44
	209	CITEDDIA: III.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	ļ	<u> </u>	1 100	

		CD TROPP in and common	TICDAM.	2002/02/10 12-16
-	3	GRIESER.in. and copper	USPAT; US-PGPUB;	2002/03/19 12:16
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	4	GRIESER.in. and meyer.in.	USPAT;	2002/03/19 12:17
İ			US-PGPUB;	1
			EPO; JPO;	
			DERWENT; IBM TDB	
l <u> </u>	10	"9900243"	USPAT;	2002/03/19 12:44
		7700243	US-PGPUB;	2002,00,15
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	"de9900243"	USPAT;	2002/03/19 12:44
			US-PGPUB;	
			EPO; JPO; DERWENT;	
	,		IBM TDB	
_	0	"de99/00243"	USPAT;	2002/03/19 12:44
			US-PGPUB;	2002, 00, 13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000100155555
-	0	(""de99/00243"").CCLS.	USPAT;	2002/03/19 12:45
1			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	o	(""99/00243"").CCLS.	USPAT;	2002/03/19 12:47
	-		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	0000/00/10 10 10
-	0	"is not identical to the sulfinic, selenic or tellurinic"	USPAT;	2002/03/19 12:49
		or tellurinic"	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"seleninic or tellurinic"	USPAT;	2002/03/19 13:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	ce	"seleninic"	IBM TDB   USPAT;	2002/03/19 12:57
-	55	SETEUTHIC	US-PGPUB;	2002/03/19 12:3/
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
-	0	("wo9940764").PN.	USPAT;	2002/03/19 12:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	o	("WO9940764").PN.	USPAT;	2002/03/19 12:58
			US-PGPUB;	,,
			EPO; JPO;	
			DERWENT;	
	_		IBM TDB	
-	0	WO009940764	USPAT;	2002/03/19 12:58
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	3	"9940764"	USPAT;	2002/03/19 12:59
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

	0	seleninic near3 tellurinic	USPAT;	2002/03/19 13:25
-		seleminic hears tellurinic	US-PGPUB;	2002/03/19 13:25
			EPO; JPO;	
			DERWENT;	
	2144	formamidine	IBM TDB USPAT;	2002/03/19 13:25
-	2144	iormamidine	US-PGPUB;	2002/03/19 13:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	323	"formamidine sulfinic acid"	USPAT;	2002/03/19 13:26
		,	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	104	"formamidine sulfinic acid" and copper	USPAT;	2002/03/19 13:26
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	"formamidine sulfinic acid" and copper and	USPAT;	2002/03/19 14:34
		etch	US-PGPUB;	
	·		EPO; JPO; DERWENT;	
			IBM TDB	
-	3	("4882202").PN.	USPAT;	2002/03/19 15:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	0	("surface.ti. rough\$5.ti.").PN.	USPAT;	2002/03/19 15:10
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	=====================================
			EPO; JPO;	
			DERWENT;	
	652210	surface.ti. rough\$5.ti.	IBM TDB USPAT;	2002/03/19 15:10
-	032210	surface.cr. rough\$5.cr.	US-PGPUB;	2002/03/19 13:10
			EPO; JPO;	
			DERWENT;	
	62		IBM TDB	2000/02/10 15:11
_	63	selenic and telluric	USPAT; US-PGPUB;	2002/03/19 15:11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	"selenic or telluric"	USPAT; US-PGPUB;	2002/03/19 15:21
	:		EPO; JPO;	
			DERWENT;	
			IBM TDB	
<b>-</b> .	0	"selenic near3 telluric"	USPAT;	2002/03/19 15:21
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	!		IBM TDB	
-	0	"selenic near4 telluric"	USPAT;	2002/03/19 15:21
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	0	"selenic near telluric"	USPAT;	2002/03/19 15:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	0	"selenic adj3 telluric"	USPAT;	2002/03/19 15:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
L	L		מטו ויוסד	<u> </u>

	0		HCDAM.	2002/03/19 15:23
-		"selenic near45 telluric"	USPAT; US-PGPUB;	2002/03/19 13:23
			EPO; JPO;	
			DERWENT;	
	0	selenic near4 telluric.	IBM TDB USPAT;	2002/03/19 15:23
_		Selenic heart terruric.	US-PGPUB;	2002/03/13 13.23
			EPO; JPO;	
			DERWENT;	
_	0	selenic near3 telluric.	IBM TDB USPAT;	2002/03/19 15:24
_		Selenic hears telluric.	US-PGPUB;	2002/03/19 13.24
			EPO; JPO;	
			DERWENT;	
	0	1	IBM TDB	2002/02/10 15-24
		selenic near2 telluric.	USPAT; US-PGPUB;	2002/03/19 15:24
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	selenic near1 telluric.	USPAT; US-PGPUB;	2002/03/19 15:24
			EPO; JPO;	
	•		DERWENT;	
			IBM TDB	
_	0	selenic near telluric.	USPAT;	2002/03/19 15:24
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	selenic and telluric.	USPAT;	2002/03/19 15:27
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	55	seleninic	USPAT;	2002/03/19 15:24
	agent control		US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	0	seleninic and tellurinic	USPAT;	2002/03/19 15:25
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	12	tellurinic	USPAT;	2002/03/19 15:25
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	63	selenic and telluric	USPAT;	2002/03/19 15:27
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	40	selenic near4 telluric	USPAT;	2002/03/19 15:27
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	8	selenic nearl telluric	USPAT;	2002/03/19 15:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	297	"copper strike"	USPAT;	2002/03/19 15:35
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	L <u> </u>		IBM TDB	<u>                                      </u>

	216	I Wanness at without and adaptate	LUCDAM:	1 2002 (02 (10 15 25 )
_	216	"copper strike" and nickel	USPAT; US-PGPUB;	2002/03/19 15:35
			EPO; JPO;	
			DERWENT;	
	175		IBM TDB	0000/03/10 15 35
-	175	"copper strike" and nickel and plate	USPAT; US-PGPUB;	2002/03/19 15:35
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	43	"copper strike" near5 nickel and plate	USPAT;	2002/03/19 15:36
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	16		USPAT;	2002/03/19 15:48
		electroplate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	2353362	roughen\$4 and adhere adn plate	USPAT;	2002/03/19 15:49
		•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1976	roughen\$4 and adhere and plate	IBM TDB USPAT;	2002/03/19 15:56
	13,0	roughency and adhere and prace	US-PGPUB;	2002/03/13 13.30
			EPO; JPO;	
		3	DERWENT;	
	2	(#6.026.750#) 733	IBM TDB	0000/00/10 16 00
_	2	("6,036,758").PN.	USPAT; US-PGPUB;	2002/03/19 16:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	3	("5,907,015").PN.	USPAT;	2002/03/19 16:11
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	·
-	2	("5,807,493").PN.	USPAT;	2002/03/19 16:19
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("5,733,599").PN.	USPAT;	2002/03/19 16:24
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	3	("5712047").PN.	USPAT;	2002/03/19 16:41
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	3	("5,554,211").PN.	USPAT;	2002/03/19 16:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	2	("5073456").PN.	USPAT;	2002/03/19 17:12
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	3	("5017271").PN.	USPAT;	2002/03/20 08:22
		· ·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	

_	3	("4642161").PN.	USPAT;	2002/03/20	08:22
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM TDB		